

What is claimed is:

1. A punch or die for compressing granules to prepare tablets where basis material is a high-silicon steel.

5 2. The punch or die according to claim 1, wherein the surface of the basis material is subjected to a carburization treatment.

Sub A1 3. ~~The punch or die according to claim 1 or 2, wherein it is applied to a punch (1, 2) or die (3) used for a tablet~~
10 machine for the preparation of tablets containing corrosive substances or adhesive substances.

4. The punch or die according to claim 3, wherein the corrosive substance is an acidic substance.

5. The punch or die according to claim 3, wherein the
15 adhesive substance(s) is/are one or more substance(s) selected from a group consisting of adhesive pharmacologically active substance, adhesive low-melting substance and adhesive excipient.

6. The punch or die according to claim 5, wherein the
20 adhesive low-melting substance is resulted due to a depression of melting point.

Sub A2 7. ~~A tablet machine which is characterized in being equipped with the punch or the die mentioned in claim 1 or 2.~~

8. A method for manufacturing tablets, characterized in
25 that, the tablet machine mentioned in claim 7 is used during compression of granules.

9. The method according to claim 8, wherein the tablets contain corrosive substances or adhesive substances.

10. The manufacturing method according to claim 9, wherein

the corrosive substance is an acidic substance.

11. The manufacturing method according to claim 9, wherein the adhesive substance(s) is/are one or more substance(s) selected from a group consisting of adhesive pharmacologically active substance, adhesive low-melting substance and adhesive excipient.

12. The manufacturing method according to claim 11, wherein the adhesive low-melting substance is resulted due to a depression of melting point.

10 ^{Sub} ~~13. Tablets~~ _{A3} which are manufactured according to the manufacturing method mentioned in any one of the claims 8 to 12.